

Title (en)

Process and platelet for the production of a cold worked workpiece out of plate and use of a platelet

Title (de)

Verfahren und Platine zur Herstellung eines kaltumgeformten Bauteils aus Stahlblech und Verwendung einer Platine

Title (fr)

Procédé et platine pour la fabrication de pièces déformés à froid à partir de tole et utilisation d'une platine

Publication

EP 1186358 A3 20031210 (DE)

Application

EP 01117697 A 20010725

Priority

DE 10044682 A 20000908

Abstract (en)

[origin: EP1186358A2] A blank is produced from a base sheet of a first steel material. A section of the base sheet is replaced by a sheet metal blank (1,2), which has different thickness and/or material characteristics from the first base sheet. Thickness, geometry of the blank, and its position in the blank are determined by the material flow during subsequent cold forming of the blank into a component, e.g. a tube (R).

IPC 1-7

B21D 22/00

IPC 8 full level

B21D 31/00 (2006.01); **B21C 37/00** (2006.01); **B21C 37/08** (2006.01); **B21C 37/15** (2006.01); **B21D 7/00** (2006.01); **B21D 22/20** (2006.01); **F01N 13/10** (2010.01)

CPC (source: EP US)

B21C 37/065 (2013.01 - EP US); **B21C 37/0815** (2013.01 - EP US); **B21C 37/15** (2013.01 - EP US); **B21D 22/201** (2013.01 - EP US); **B21D 35/006** (2013.01 - EP US); **Y10T 29/49771** (2015.01 - EP US); **Y10T 29/49798** (2015.01 - EP US); **Y10T 29/49805** (2015.01 - EP US)

Citation (search report)

- [XY] EP 0869265 A1 19981007 - PROTOTECHNIK GMBH [DE]
- [Y] EP 0620056 A1 19941019 - GEN MOTORS CORP [US]
- [XA] DE 4104256 A1 19920820 - THYSSEN LASER TECHNIK GMBH [DE]
- [A] WO 9962669 A1 19991209 - ELPATRONIC AG [CH], et al

Cited by

EP3321026A1; EP3752313A4; WO2019226136A2

Designated contracting state (EPC)

AT BE CH CY DE DK ES FI FR GB GR IE IT LI LU MC NL PT SE TR

DOCDB simple family (publication)

EP 1186358 A2 20020313; **EP 1186358 A3 20031210**; CZ 20012750 A3 20030212; CZ 297850 B6 20070418; DE 10044682 A1 20020418; DE 10044682 C2 20020829; JP 2002126823 A 20020508; US 2002035772 A1 20020328; US 6883218 B2 20050426

DOCDB simple family (application)

EP 01117697 A 20010725; CZ 20012750 A 20010730; DE 10044682 A 20000908; JP 2001252482 A 20010823; US 94688201 A 20010904